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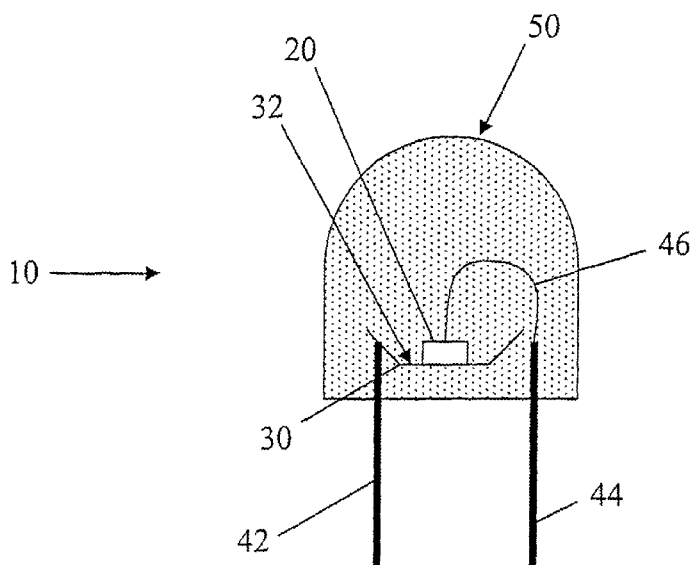
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(54) Title: EPOXY MOLDING COMPOUNDS CONTAINING PHOSPHOR AND PROCESS FOR PREPARING SUCH COMPOSITIONS



(57) Abstract: A molding compound for use in encapsulating electronic packages which include an optoelectronic component, such as an LED, is provided. The molding compound of the present invention includes a partially cured epoxy composition having a phosphor material substantially uniformly distributed throughout the epoxy composition. The phosphor material may be suspended within the epoxy composition by pre-reacting a portion of the epoxy composition prior to B-staging of the molding compound. As such, the phosphor material is suspended within the epoxy composition, thereby preventing settling of the phosphor material during B-staging, as well as during curing of the molding compound in the encapsulation process.



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**Declarations under Rule 4.17:**

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